

PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE RESIN SHEET,
HOLLOW STRUCTURE, CURED MATERIAL, HOLLOW STRUCTURE PRODUCTION
METHOD, ELECTRONIC COMPONENT, AND ELASTIC WAVE FILTER

ABSTRACT

An object of the present invention is to provide a resin composition that can form an insulating film that is excellent in pattern-processability and pressure resistance and has high reliability and can be applied to a substrate and the like required to have a high elastic modulus and a high resolution. There is provided a photosensitive resin composition containing a polymer (A), a glass filler (B), a photopolymerizable compound (C), a photopolymerization initiator (D), and a thermal crosslinking agent (E), in which the glass filler (B) contains at least two selected from the group consisting of silicon oxide, aluminum oxide, and boron oxide, and further contains a rare earth oxide.

[FIG. 1A]